Final Product Change Notification 201607004F01

Issue Date: 13-Jul-2016
Effective Date: 28-Oct-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab Process
[ ] Wafer Fab Materials
[ ] Wafer Fab Location
[ ] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling
[ ] Test Location
[ ]Test Process
[ ] Test Equipment
[ ] Design
[ ] Errata
[ ] Electrical spec./Test coverage

Introduction of new CLIP CD0S for PSMN4R0-60YS. Including change of solder.

Details of this Change

CD0S is a new clip design to be introduced for use in PSMN4R0-60YS. The solder material will change from PbSn to PbSnAg for standardization.

Why do we Implement this Change

Improved product quality and reliability.

Identification of Affected Products

Product identification does not change
Cut-off date code identifies affected products.

Product Availability

Sample Information

Samples are available upon request

Impact

no impact to the product's functionality anticipated.
No change to form, fit or function.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201509011F01	14-Sep-2015	28-Dec-2015	Introduction of New Clips CD0S and LCD0S for max die Trench 6 in LFPAK and LFPAK2.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Aug-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name powermospcn@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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